

FIG. 1
(PRIOR ART)

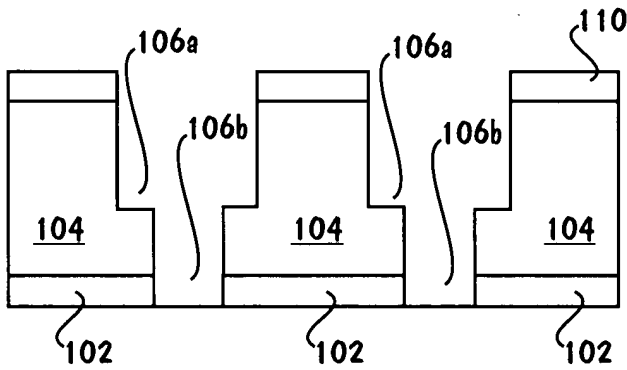


FIG. 2
(PRIOR ART)

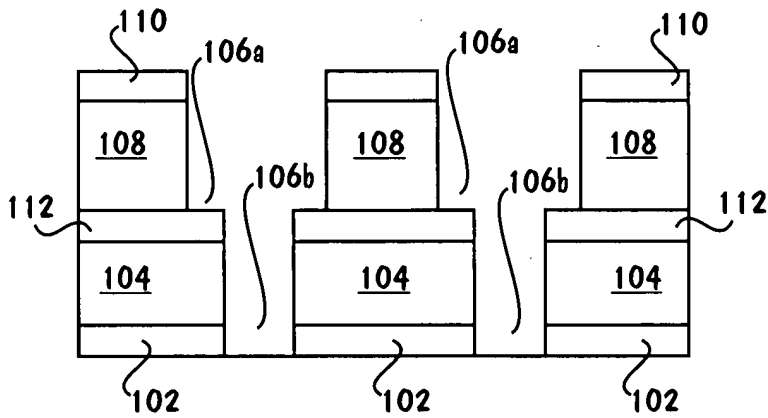


FIG. 3
(PRIOR ART)

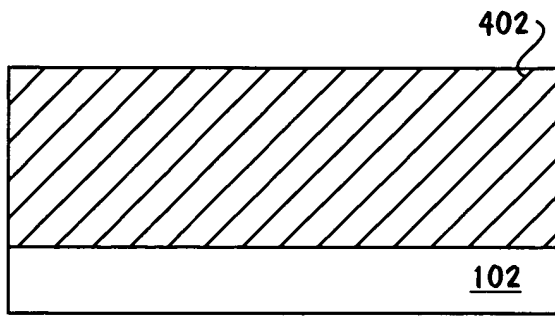


FIG. 4

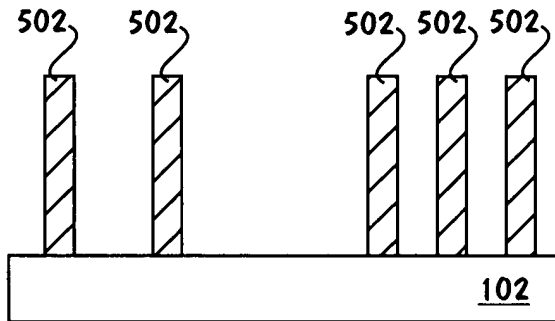


FIG. 5

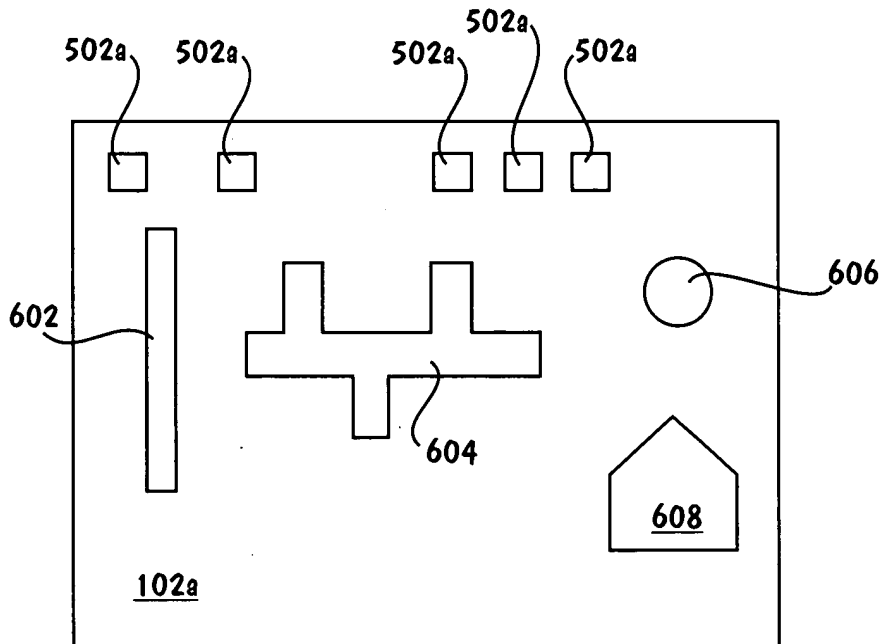


FIG. 6

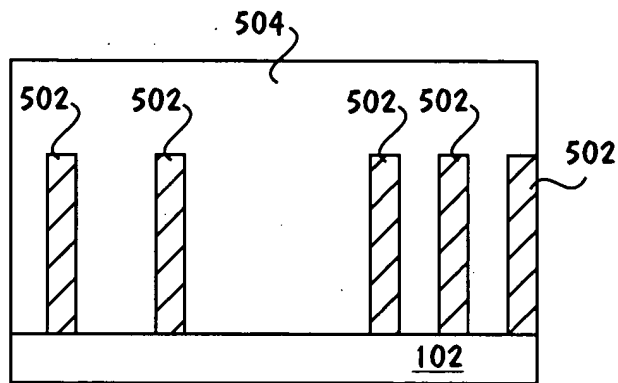


FIG. 7

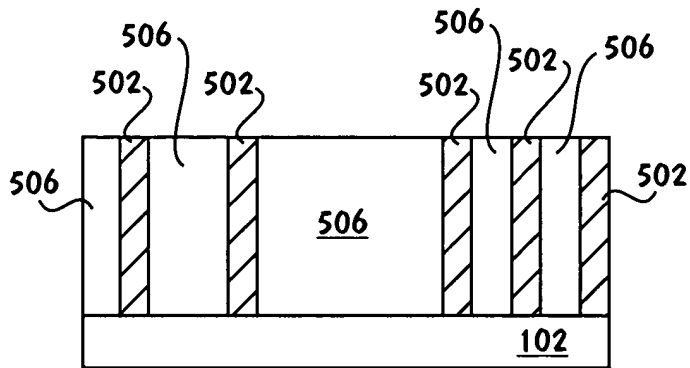


FIG. 8

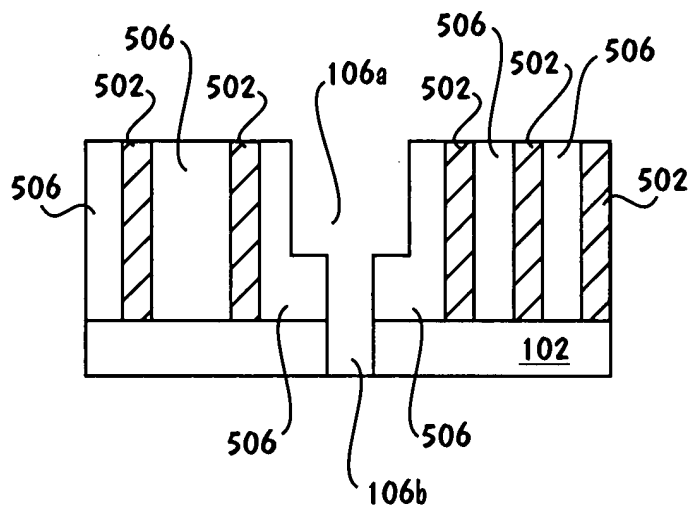


FIG. 9

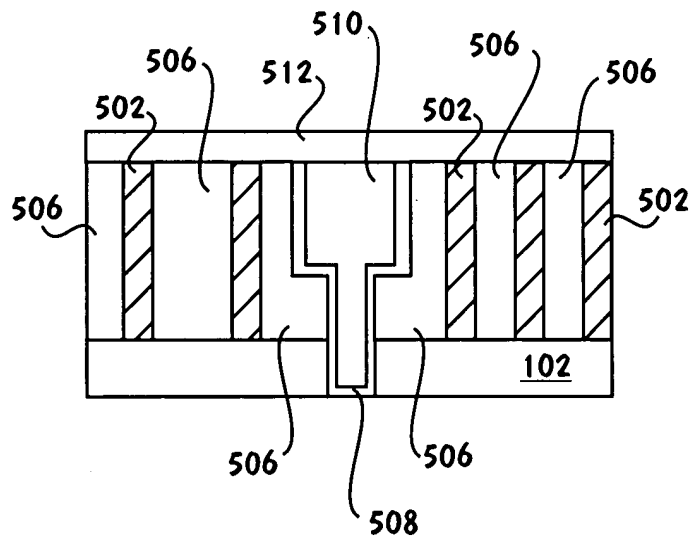


FIG. 10

FORM AT LEAST ON VERTICALLY-ORIENTED NON-CONDUCTIVE
REINFORCING STRUCTURE ON A SUBSTRATE

702

FORM A DIELECTRIC LAYER SURROUNDING THE
REINFORCING STRUCTURE

704

FIG. 11

FORM A FIRST DIELECTRIC LAYER OVER METAL
CONDUCTORS AND AN INTRALAYER DIELECTRIC

802

FORM A SECOND SECOND DIELECTRIC LAYER OVER THE FIRST
DIELECTRIC LAYER

804

PATTERN THE SECOND DIELECTRIC LAYER TO FORM
REINFORCING STRUCTURES

806

FORM A THIRD DIELECTRIC LAYER OVER AND ADJACENT
THE PATTERNED SECOND DIELECTRIC

808

PLANARIZE THE THIRD DIELECTRIC LAYER

810

FORM INLAID METAL INTERCONNECTION IN THE THIRD DIELECTRIC LAYER

812

FIG. 12